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SPECIFICATION FOR TFT MODULE

MODULE NO: AFY800480B0-5.0N12NTM-R REVISION NO: A

Customer's Approval:

	SIGNATURE	DATE
PREPARED BY (RD ENGINEER)		
CHECKED BY		
APPROVED BY		

REVISION RECORD

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0	2016-03-10	First release	Preliminary
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1. GENERAL INFORMATION

No.	Item	Contents	Unit
1	LCD size	5.0 inch (Diagonal)	/
2	LCD type	TN/Normally white/Transmissive(Anti-glare)	/
3	Viewing direction(eye)	12 O'clock	/
4	Gray scale inversion direction	6 O'clock	/
5	Resolution(H*V)	800 *480 Pixels	/
6	Module size (L*W*H)	120.70*75.80*3.95	mm
7	Active area (L*W)	108.00*64.80	mm
8	Pixel pitch (L*W)	0.135*0.135	mm
9	Interface type	RGB interface	/
10	Module power consumption	1.274(with backlight)	W
11	Back light type	LED	/
12	Driver IC	ILI6122+ILI5960 OR COMPATIBLE	/
13	Weight	74.6	g

2. ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Min.	Max.	Unit
Power supply input voltage(TFT Module)	VDD	-0.3	5.0	V
Backlight current (normal temp.)	ILED	-	50	mA
Operation temperature	Тор	-20	70	°C
Storage temperature	Tst	-30	80	°C
Humidity	RH	-	90%(Max60 °C)	RH

3. ELECTRICAL CHARACTERISTICS DC CHARACTERISTICS(at Ta=25°C)

Item	Symbol	Min.	Тур.	Max.	Unit	Note
Power supply input voltage(TFT Module)	VDD	3.0	3.3	3.6	V	
I/O logic voltage	VDDIO	N/A	N/A	N/A	V	
Input voltage 'H' level	VIH	0.7VDDI	-	VDDI	V	
Input voltage 'L' level	VIL	VSS	-	0.3VDDI	V	
Power supply current	IVDD	-	127.2	-	mA	
TFT gate on voltage	VGH	-	N/A	-	V	
TFT gate off voltage	VGL	-	N/A	-	V	
Analog power supply voltage	AVDD	-	N/A	-	V	
Differential input common mode voltage	Vcom	-	N/A	-	V	

4. BACKLIGHT CHARACTERISTICS

(at Ta=25°C,RH=60%)

Item	Symbol	Min.	Тур.	Max.	Unit	Note
LED forward voltage	VF	-	18.6	19.8	V	IF=20*2mA
LED forward current	IF	-	40	-	mA	
LED power consumption	PLED	-	0.744	-	W	Note1
Number of LED	-		12		PCS	
Connection mode	-	6 in s	eries 2 in pa	/		
LED life-time	-	20000	-	-	Hrs	Note2

Note1 : Calculator value for reference : IF*VF = PLED

Note2 : The LED life-time define as the estimated time to 50% degradation of initial brightness at Ta= 25° C and IF =40mA. The LED lifetime could be decreased if operating IF is larger than 40mA.

5. TOUCH PANEL CHARACTERISTICS

(at Ta=25°C)

FPC Design	Item	Description	Note
	IC solution on TP Model	-	
	Touch Count Max	-	
	Display Resolution*	-	
[√] COF	Interface Type *	-	
	I2C Slave Address*	-	
	Origin of Coordinate*	-	
	IC solution on Broad*	-	
[] COB	Driving Channels	-	
	Sensing Channels	-	

Parameter	Min.	Тур.	Max.	Unit
Interface Signal Voltage*	-	-	-	V
Power Voltage*	-	-	-	V
Power ripple*	-	-	-	MV

Note1 : The detail refer to the Specification For IC.

Note2 : "*" means that the item is optional according to the product requirement.

6. EXTERNAL DIMENSIONS



Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Remark	Note
Response time	Tr+ Tf		-	25	50	ms	FIG.1	Note 4
Contrast ratio	Cr	-	400	500	-	-	FIG.2	Note 1
Surface Iuminance	Lv	θ=0°	300	380	-	cd/m ²	FIG.2	Note 2
Luminance uniformity	Yu	θ=0°	75	80	-	%	FIG.2	Note 3
NTSC	-	θ=0°	-	50	-	%	FIG.2	Note 5
	e θ	Ø = 90°	60	70	-	deg	FIG.3	Note 6
		Ø =270°	40	50	-	deg	FIG.3	
Viewing angle		Ø = 0°	60	70	-	deg	FIG.3	Note 6
		Ø=180°	60	70	-	deg	FIG.3	
	Red x		0.5249	0.5649	0.6049	-		
	Red y		0.2985	0.3385	0.3785	-		
	Green x		0.3050	0.3450	0.3850	-		
CIE (x,y)	Green y	θ=0°	0.5369	0.5769	0.6169	-	FIG.2	Note F
chromaticity	Blue x	Ø=0° Ta=25°C	0.1086	0.1486	0.1886	-	CIE1931	Note 5
	Blue y	10-20 0	0.0572	0.0972	0.1372	-]	
	White x		0.2743	0.3143	0.3543	-		
	White y		0.3026	0.3426	0.3826	-		

7. ELECTRO-OPTICAL CHARACTERISTICS

Note1.Definition of contrast ratio

Contrast ratio(Cr) is defined mathematically by the following formula.

For more information see FIG.2.

Contrast ratio= <u>Luminance measured when LCD on the "White" state</u> Luminance measured when LCD on the "Black" state

Measured at the center area of the LCD

Note2.Definition of surface luminance

Surface luminance is the luminance with all pixels displaying white.

For more information see FIG.2.

Lv = Average Surface Luminance with all white pixels(P1,P2,P3,,Pn)

Note3.Definition of luminance uniformity

The luminance uniformity in surface luminance is determined by measuring luminance at each test position 1 through n, and then dividing the maximum luminance of n points luminance by minimum luminance of n points luminance.For more information see FIG.2.

Minimum surface luminance with all white pixels (P1,P2,P3,.....,Pn) Yu =

Maximum surface luminance with all white pixels (P1,P2,P3,.....,Pn)

Note4. Definition of response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%. For additional information see FIG1.

Note5. Definition of color chromaticity (CIE1931)

CIE (x,y) chromaticity, The x,y value is determined by screen active area center position P5. For more information see FIG.2.

Note6. Definition of viewing angle

Viewing angle is the angle at which the contrast ratio is greater than 10. angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG.3.

For viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope or DMS series Instruments or compatible. For contrast ratio, Surface Luminance, Luminance uniformity and CIE, the testing data is base on TOPCON's BM-5or BM-7 photo detector or compatible.

Note: For TFT module, Gray scale reverse occurs in the direction of panel viewing angle.

FIG.1. The definition of response Time



FIG.2. Measuring method for contrast ratio, surface luminance, luminance uniformity, CIE (x,y) chromaticity

Size : $S \le 5$ "(see Figure a) A : 5 mm B : 5 mm H,V : Active area Light spot size $\emptyset = 5$ mm(BM-5) or $\emptyset = 7.7$ mm (BM-7)50cm distance or compatible distance from the LCD surface to detector lens. test spot position : see Figure a. measurement instrument : TOPCON's luminance meter BM-5 or BM-7 or compatible (see Figure c).







Size : 5" < S≤12.3"(see Figure b) H,V : Active area

Light spot size \emptyset =5mm(BM-5) or \emptyset =7.7mm (BM-7)50cm distance or compatible distance from the LCD surface to detector lens. test spot position : see Figure b.

measurement instrument : TOPCON's luminance meter BM-5 or BM-7 or compatible (see Figure c).



FIG.3. The definition of viewing angle



8. INTERFACE DESCRIPTION

TFT Module Inter Interface No.	Name	I/O or connect to	Description
1	LEDK	Р	Power for LED backlight(Cathode)
2	LEDA	Р	Power for LED backlight(Anode)
3	CS(NC)	/	No connection
4	VDD	Р	Power for LCD
5-12	Red(0-7)	I	Red data signal
13-20	Green(0-7)	I	Green data signal
21-28	Blue(0-7)	I	Blue data signal
29	GND	I	Ground
30	DCLK	I	Dot clock signal
31	DISP	I	Display on/off
32	HSYNC	I	Horizontal sync input.
33	VSYNC	I	Vertical sync input
34	DE	I	Data enable
35	SCL(NC)	/	No connection
36	SDA(NC)	/	No connection
37	XR	I	TP:X right
38	YD	I	TP:Y bottom
39	XL	I	TP:X left
40	YU	I	TP:Y top

9. AC CHARACTERISTICS

Parameter	Symbol		Spec		Unit	Conditions		
	Symbol	Min.	Тур.	Max.	Onic			
VDD Power ON slew rate	t _{POR}			20	ms	0V ~ 0.9VDD		
RSTB pulse width	t _{RST}	10			us	CLKIN=50MHz		
CLKIN cycle time	t _{CPH}	20		_	ns			
CLKIN pulse duty	t _{сwн}	40	50	60	%			
VSD setup time	t _{vst}	8	1		ns			
VSD hold time	t _{VHD}	8			ns			
HSD setup time	t _{HST}	8	-	-	ns			
HSD hold time	t _{HHD}	8			ns			
Data setup time	t _{DST}	8	-		ns	D0[7:0], D1[7:0], D2[7:0] to CLKIN		
Data hold time	t _{DHD}	8		-	ns	D0[7:0], D1[7:0], D2[7:0] to CLKIN		
DE setup time	t _{EST}	8			ns			
DE hold time	t _{ehd}	8			ns			
Output stable time	V			6		10% to 90% target voltage.		
Output stable time	ISST			0	us	CL=120pF, R=10KΩ		
CLKIN frequency	✓f _{CLK}		40	50	MHz	VDD=3.0 ~ 3.6V		
CLKIN cycle time	t _{cLK}	20	25		ns			
CLKIN pulse duty	t _{cwн}	40	50	60	%	Тсік		
Time from HSD to Source output	t _{HSO}		20		CLKIN			
Time from HSD to LD	t _{HLD}		20		CLKIN	Note (2)		
Time from HSD to STV	t _{HSTV}		2		CLKIN			
Time from HSD to CKV	t _{нскv}		20		CLKIN			
Time from HSD to OEV	t _{HOEV}		4		CLKIN			
LD pulse width	t _{wLD}		10		CLKIN	Note (2)		
CKV pulse width	t _{wckv}		66		CLKIN			
OEV pulse width	twoev		74		CLKIN			

Note: (1) VDD=3.0 ~ 3.6V, VDDA=6.5~13.5V, DGND=AGND=0V, Ta=-20~+85 °C

(2) The contents of the data register are transferred to the latch circuit at the rising edge of LD. Then the

gray scale voltage is output from the device at the falling edge of LD.

(3) Output loading condition :





Horizontal Input Timing									
Derement	Parameter			Value					
Paramet	er	Symbol	Min.	Тур.	Max.	Unit			
Horizontal disp	lay area	t _{HD}		800	-	CLKIN			
CLKIN frequ	Jency	fclk		33.3	50	MHz			
1 Horizontal lin	e period	t _H	862	1056	1200	CLKIN			
	Min.			1		CLKIN			
HSD pulse width	Тур.	t _{HPW}				CLKIN			
width	Max.			40		CLKIN			
HSD back porch	SYNC	t _{HBP}	46	46	46	CLKIN			
HSD front porch	SYNC	t _{HFP}	16	210	354	CLKIN			

Vertical Input Timing							
Parameter	Symbol		Value		Unit		
Falameter	Symbol	Min.	Тур.	Max.	Unit		
Vertical display area	t _{vp}	-	480	_	HSD		
VSD period time	tv	510	525	650	HSD		
VSD pulse width	t _{vPW}	1		20	HSD		
VSD back porch	t _{veP}	23	23	23	HSD		
VSD front porch	t _{VFP}	7	22	147	HSD		



typw VS. HS. DE tyb tyfp tvd tv

10. POWER SEQUENCE

To prevent the device damage from latch up, the power ON/OFF sequence shown below must be followed.

Power ON: VDD, DGND \rightarrow VDDA, AGND \rightarrow V1 to V14 Power OFF: V1 to V14 \rightarrow VDDA, AGND \rightarrow VDD, DGND

In order to prevent ILI6122 from power ON reset fail, the rising time (t_{POR}) of the digital power supply VDD should be maintained within given specifications. The power ON/OFF timing sequence is illustrated as below:



Note: For prevent anormal operation, t_{RST} must be longer than 10us during Power ON sequence.

11. RELIABILITY TEST CONDITIONS

No.	Test item	Test condition	Inspection after test
11.1	High temperature storage	80±2°C/240 hours	
11.2	Low temperature storage	-30±2°C/240 hours	
11.3	High temperature operating	70±2°C/120 hours	Inspection after 2~4hours storage at
11.4	Low temperature operating	-20±2°C/120 hours	room temperature, the sample shall be free
11.5	Temperature cycle	-20±2°C~25°C~70±2°C*10cycles (30min.) (5min.) (30min.)	from defects : 1.Current changing
11.6	Damp proof test	50°C*90% RH/120 hours	value before test and after test is 50% larger;
11.7	Vibration test	Frequency : 10Hz~55Hz~10Hz Amplitude : 1.5mm , X , Y , Z direction for total 3hours (Packing condition)	 2. Function defect : Non-display,abnormal-di splay,missing lines, Short lines,ITO corrosion; 3. Visual defect : Air
11.8	Dropping test	Drop to the ground from 1m height, one time, every side of carton. (Packing condition)	bubble in the LCD,Seal leak,Glass crack.
11.9	ESD test	Voltage : $\pm 8KV$ R : 330Ω C : $150pF$ Air discharge, 10time	

Remark :

1. The test samples should be applied to only one test item.

2.Sample size for each test item is 3~5pcs.

3.For damp proof test, Pure water(Resistance>10M Ω) should be used.

4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.

5.EL evaluation should be excepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has. 6.Failure judgment criterion: Basic specification, Electrical characteristic, Mechanical characteristic, Optical characteristic.

12. INSPECTION CRITERION

12.1 Objective

The TFT test criterion are set to formalize TFT quality standards for ODNA with reference to those of the customer for inspection, release and acceptance of finished TFT products in order to guarantee the quality of TFT products required by the customer.

12.2. Scope

The criterion is applicable to all the TFT products manufactured by ODNA.

12.3. Equipment for Inspection

Electrical tester, electrical testing machines, vernier calipers, microscopes, magnifiers, anti-static wrist straps, finger cots, labels, tri-phase cold and hot shock machine, constant temperature and humidity chamber, backlight table, ovens for high-low temperature experiments, refrigerators, constant voltage power supply (DC), desk Lamps, etc.

12.4. Sampling Plan and Reference Standards

12.4.1 Sampling plan :

Refer to National Standard GB/T 2828.1---2012/ISO2859-1:1999, level II of normal levels :

Major defect: AQL 0.4

Minor defect: AQL 1.0

12.4.2 GB/T 2828.1---2012/ISO2859-1:1999 Sampling check procedure in count

12.4.3 GB/T 18910. Standard for LCM parts

12.4.4 GB/T24213-2008 Basic Environmental Test Procedures for Electrical and Electronic Products 12.4.5 IPC-A-610E Acceptability of Electronic Assemblies

12.5. Inspection Conditions and Inspection Reference

12.5.1 Cosmetic inspection: shall be done normally at 23±5°C of the ambient temperature and 45~75%RH of relative humidity, under the ambient luminance between 500lux~1000lux and at the distance of 30cm apart between the inspector's eyes and the LCD panel and normally in reflected light. For backlight LCM, cosmetic inspection shall be done under the ambient luminance less than 100lux with the backlight on.

12.5.2 The TFT shall be tested at the angle of 45°left and right and 0-45° top and bottom as the following picture showing:



12.5.3 Definition of viewing area(VA)

A area : Active area(AA area)

B area : Viewing area(VA area)

C area : Non-viewing area(not viewing after customer assembly)

If there is any appearance viewing defect which do not affect product quality and customer assembly in C area, it's accepted in generally.

The criteria apply to A and B area except chipping and crack.





12.5.4 Inspection with naked eyes(exclusive of the inspection of the , with magnifiers)12.5.5 ND card use instruction

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12.5.6 Undefined items or other special items, refer to mutual agreement and limited sample. If criterion does not match product specifications/ technical requirement, both should be subject to special inspection criterion agreed by customer.

12.6. Defects and Acceptance Standards

12.6.1 Electrical properties test

12.6.1.1 Test voltage(V) : Refer to the instruction of testers and the product specification or drawing and the display content and parameters and display effects shall conform to the product specification and drawing. 12.6.1.2 Current Consumption(I) : Refer to approved product specifications or drawings.

No.	Defects	Descriptions	Pictures	Inspection method/tools	Defect category
12.6.1.3.1		shows no picture/display in normal connected situation.		Naked eyes/ testers	MA.
12.6.1.3.2	Missing segment	Shows missing lines in normal display		Naked eyes/ testers	MA.
12.6.1.3.3	Sealing Defect	Shows defect in any display around LCD liquid crystal sealant area		Naked eyes/ testers	MA.
12.6.1.3.4	POL angle defect	Not accepted	正常 POL版权180度后	Naked eyes/ testers	MA.
12.6.1.3.5	Image retention (sticking)	The previous picture stays in the next picture.Disappear time <10s, OK; time>10s, NG		Naked eyes/ testers	MA.
12.6.1.3.6	Flicker	Not accepted		Naked eyes/ testers	MA.
12.6.1.3.7	Display abnormal	Not accepted		Naked eyes/ testers	MA.
12.6.1.3.8	Cross-talk	Refer to limited sample	+	Naked eyes/ limited sample	MA.
12.6.1.3.9	Display dim/bright	Refer to limited sample	/	Naked eyes/ limited sample	MA.
12.6.1.3.10	Contrast	Refer to limited sample	/	Naked eyes/ limited sample	MA.
12.6.1.3.11	Huge current	Out of spec, not accepted	/	Ammeter	MA.
12.6.1.3.12	TP function defect	Not accepted	/	Naked eyes/ Touch/ test program	MA.

12.6.1.3 Function items(Defect category : MA.)

12.6.2 LCD dot/line defect

12.6.2.1 LCD pixel dot defect(defect category : MI.)

	ltem				Inspe	ctio	on criterior	า	
	Size		S<	:5"		5"≤S<10"			S<15"
Color pixel do	t defect(RG	B dot)	-			2			2
2 connected b	oright dot		()		1			1
3 connected b	3 connected bright dot or more		()	0		1		
Bright dot qua	intity		1			2		3	
Random dark	dot quantity	,	2	2		3		4	
2 connected c	lark dot		1			1			2
3 connected c	lark dot or m	nore	()		0			0
Dark dot quar	itity		3	3		4			5
Multi-bright do	ot				ND 3	3%ł	nidden, OK		
Remark: 2 brig	ght dots dist	ance DS≥	:15mm 2	dark dots	distance D	S≥5	ōmm		
1) Bright dot:	Power on Th	T and RG	GB dot in b	olack displa	ау				
2) Dark dot: P	ower on TF	T and gray	y or black	dot in RGE	3 display				
3) Multi-bright	dot: Power	on TFT ar	nd fluores	cent tiny do	ot in black o	disp	lay(only vis	ible in black o	display)
12.6.2.2 LCD a	appearance	dot defec							
No.	Item			spection c				Picture	Inspection
			ze	S<5"	5"≤S<10"		0"≤S<15"		method/tools
					Not count		0≤0.2mm		
			D≤0.25	3	3		lot count		Naked eyes
			D≤0.30	1	2		2~0.35mm	a	/film card /magnifier
40.0.0.4	Dot defect		D≤0.35	0	1		Q'ty ≤ 4	D (a,b)/2	
12.6.2.2.1	(black dot,		D≤0.50	0	0		1	D=(a+b)/2	_
	white dot)		>0.5	0	0		0		
					nt.Multi-dot	t as	bulk is not	accepted.	
			t quantity≤		4				
				ar dois in	r cm is judų	jea	as multi-do	λ.	
		Length (mm)	Width	S<5"	5"≤S<10"	10	0"≤S<15"		
		Not	(mm)					1.0	
		count	W≤0.03	Accepted	Accepted	A	Accepted		
		count	0.03≤W						Naked eyes
	Line	L≤5	<0.05	3	3	1	Not count	N T	/film card
	defect		<0.00 0.05≤W						/magnifier
12.6.2.2.2	(visible	L≤5	<0.08	0	1		3		, magimiei
	when		0.05≤W					(
	power on)	L≤8	<0.08	0	0		1		
	·	L>8	W>0.08	0				`_ *	
		Remark :							
		Invisible v	when pow	er on,only	visible in sp	beci	ial angle ac	jainst light, sh	ow as
			•	•	•		• •	ontrol or refei	
		sample.	_						
	Polarizer	Size	e(mm)	S<5"	5"≤S<10	0"	10"≤S<15	3	
	convex-	D≤	0.20	Not coun	t Not cou	Int	Not coun	t	
	concave	0.20	<d≤0.5< td=""><td>2</td><td>2</td><td></td><td>0</td><td></td><td>Naked eyes</td></d≤0.5<>	2	2		0		Naked eyes
12.6.2.2.3	dot defect,	0.50	<d≤0.8< td=""><td>0</td><td>1</td><td></td><td>3</td><td>1b</td><td>/film card</td></d≤0.8<>	0	1		3	1 b	/film card
	polarizer	0.8<	:D≤1.5	0	0		1	/magnifie	
	bubble	ר~ח	D>1.5mm 0		0				
	defect			0	0		0		

12.6.3 Chipping defect

No.	Item		Accepte	d criterion(mm)		MA.	MI.
12.6.3.1	ITO conductive side	Х	/	≤1/8L	1		
		Y	Y≤1/6W	1/6W <y≤1 4w<="" td=""><td>1/4W <y< td=""><td></td><td></td></y<></td></y≤1>	1/4W <y< td=""><td></td><td></td></y<>		
	Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z	Accept	2	2	0		\checkmark
	Corner chipping	х	/	≤1/6L	/		
	(ITO pins position)	Y	Y≤1/2W	1/2W <y≤w< td=""><td>W <y< td=""><td></td><td></td></y<></td></y≤w<>	W <y< td=""><td></td><td></td></y<>		
12.6.3.2	· ·	Accept	2	1	0		
		per 6.3.3; a black borde	at the same er of the fra	ed in sealed edge time it should no ame and the corn ection position per	t enter into er chipping		
	Chipping in sealed area (outside chipping)	Х	/	≤1/8L	/		
		Y(outside chipping)	Not enter	Enter Y≤H	H <y< td=""><td></td><td></td></y<>		
		Y(inside chipping)	into sealant	Enter Y≤1/2H	1/2H <y< td=""><td></td><td></td></y<>		
12.6.3.3		Z	≤T	≤1/2T	/		
	IZ I	Accept	2	1	0		
	Chipping in sealed area (inside chipping)	sealing are in the oppo	a are same site of stage	r and outer chippir . When the chippir e, Y as per the chip andard in 6.3.1	ng occurred		
	Conductive side (back side chipping)	х	/	≤1/6L	/		
	v v	Y	Y≤1/3W	1/3W <y≤2 3w<="" td=""><td>2/3W <y< td=""><td></td><td></td></y<></td></y≤2>	2/3W <y< td=""><td></td><td></td></y<>		
12.6.3.4	Z Z	Accept	2	2	0		
	x [×] ,	Chipping in	to ITO side,	refer to 6.3.1			
	Protruding LCD poor cutting and LCD burrs	х	/	≤1/8L	/		
		Y	≤1/6W	1/6W <y≤1 5w<="" td=""><td>1/5W <y< td=""><td></td><td></td></y<></td></y≤1>	1/5W <y< td=""><td></td><td></td></y<>		
12.6.3.5	t b	Z	/	/	/		v
		Accept	1	1	1		
		The outside drawing.	e protruding	control as per the	tolerance of		

12.6.3.6	Crack	Not allow to occur cracks without direction; the crack expand to inside is NG, but to outside is OK (confirmed as per the damaged standard)				
Remark :						
X means the	e length of chipping;					
Y means the	width;					
Z means the	thickness;					
W means the	W means the step width of the two glasses;					
H means the	e distance from the glass e	dge to the sealant inner edge;				
T means glas	ss thickness.					

12.6.4 Backlight components

No.	ltem	Description	Accepted criterion	MA.	MI.
12.6.4.1	No backlight wrong Color	/	Rejected	\checkmark	
12.6.4.2	Color deviation	When powered on, the LCD color differs from its sample and found that the color not conforming to the drawing after testing.	Refer to sample and drawing		
12.6.4.3	Brightness deviation	When powered on, the LCD brightness differs from its sample and is found after testing not conforming to the drawing; or if it conforms to the drawing but the brightness over ±40% than its typical value.	Refer to sample and drawing		V
12.6.4.4	Uneven brightness	Uneven on the same LCD and out of the specification of the drawing. The no specification evenness= (the max value-the min value)/ mean value< 70%.	Refer to sample and drawing		\checkmark
12.6.4.5	Spot/line/ scratch	When power on, it has dirty spot, scratches and so on spot and line defects.	Refer to 6.2.2		\checkmark

12.6.5 Metal frame (Metal Bezel)

No.	Item	Description	Accepted criterion	MA.	MI.
12.6.5.1	Material & surface treatment	Metal frame/surface treatment do not conform to the specifications.	Rejected	\checkmark	
12.6.5.2	Tab twist Unconformity /Tab not twisted	Wrong twist method or direction and twist tabs are not twisted as required.	Rejected	\checkmark	
12.6.5.3	Bezel paint loss	1.Front surface : Paint peel off and scratch to the			\checkmark
12.6.5.4	Bezel scratch	bottom Dot:D≤0.5mm, exceeds 3;			\checkmark
12.6.5.5	Painting peel off, discoloration, dent, and scratch	Line:L≤3.0mm,W≤0.05mm exceeds 2; 2.Front dent, air bubble and side with paint peeling off scratch to the bottom Dot: D≤1.0mm, exceeds 3; Line:L≤3.0mm,W≤0.05mm, exceeds 2;	bottom Dot:D≤0.5mm, exceeds 3; Line:L≤3.0mm,W≤0.05mm exceeds 2; Rejected 2.Front dent, air bubble and side with paint peeling off scratch to the bottom Dot: D≤1.0mm, exceeds 3;		\checkmark

12.6.5.6	Burr	Burr(s) on metal bezel is so long as to get into viewing area.	Rejected		\checkmark
12.6.6 FPC					
No.	Item	Description	Accepted criterion	MA.	MI.
12.6.6.1	Model &P/N	Material model & P/N	Keep the same with drawing and technical requirement	\checkmark	
12.6.6.2	Dimension/ position	Dimension in drawing spec	f≤1/3w, h ≤1/3H, dimension in drawing spec-> OK Conducive material and ITO/PDA connective area must over than 1/2. Entire dimension must be in spec tolerance.		V
12.6.6.3	FPC appearance	Hot pressing material get broken, folding line open; FPC golden finger oxidate, broken ,scratch ,foreign material which cause line short	Broken length<2mm; FPC line is OK- > Accepted Crack and line broken->Rejected		V
12.6.6.4	FPC burr	Burr near FPC edge area	When cover line and burr length ≤1.0mm->Accepted		\checkmark
12.6.6.5	FPC falling off	FPC bonding area falling off ; silica gel breaking	Rejected		\checkmark
11.6.6.6	Sealant missing ITO line	Sealant is not covered all ITO line	Rejected		
12.6.6.7	Missing sealant	No sealant	Rejected	\checkmark	
12.6.6.8	Sealant	Sealant height ->product total height	Rejected	\checkmark	
12.6.7 SMT					
No.	ltem	Description	Accepted criterion	MA.	MI.
12.6.7.1	Soldering bridge	Solder between adjacent pads and components	Rejected		V

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12.6.7.2	Solder ball/splash	Solder ball/tin dross causing short circuit at the solder point. There are active solder ball and splash.	Rejected		\checkmark
12.6.7.3	Soldering excursion	Soldering slant > 1/3 soldering pad	Rejected		V
12.6.7.4	Component wrong	Component on PCB differs with drawing: wrong one, extra one,lack one,opposite polarity	Rejected	\checkmark	
	attaching	JUMP short circuit on PCB: extra soldering ,lack soldering.	Rejected	\checkmark	
12.6.7.5	Component falling off	Soldering but component is missing	Rejected	\checkmark	
11.6.7.6	Wrong component	Component model/spec differs from product specification	Rejected	\checkmark	
12.6.8 Genera	I Appearance				r
No.	ltem	Description	Accepted criterion	MA.	MI.
12.6.8.1	Dimension	According to drawing	Accepted	\checkmark	
12.6.8.2	Surface stain	Defect mark or label are not removed residual glue, and finger print,etc;	Rejected		\checkmark
12.6.8.3	Assembly foreign material	Dot/linear stain after assembly backlight and diffuse film TP assembly fogy stain	Invisible when power on->OK Refer to 6.2.2 dot/line spec		\checkmark
12.6.8.4	Mixture	Different model product in the same shipment	Rejected	\checkmark	
12.6.8.5	Product mark	Missing, unclear, incorrect, or misplaced part	Rejected		\checkmark
12.6.8.6	Componen t mark	Silk screen mark clear, resistance measured value in spec	Accepted (Refer to customer special requirement)		\checkmark
12.6.8.7	Newton's rings	Area<1/6 screen area quantity≤1	Accepted		\checkmark
12.6.8.8	Mura	1.In black display ND 3% invisible ->OK; visible->NG 2.Naked eyes inspection RGB display invisible Black display, area<1/4 screen area	Refer to limited sample		\checkmark

12.6.8.9	Light leak	1.LCD edge(near backlight) shadow by LCD lamps irregular illuminate 2.Judge in black/white/gray display (slight leaky is yellowish,greenish, blueish ->NG); Tape 浮起漏光	Refer to limited sample	V
12.6.8.10	Polarizer	 1.Polarizer slant.Cover VA and not over LCD edge 2.No unmovable stain or finger print in polarizer VA 3.Bubble/warped but not enter VA 	Accepted	\checkmark
12.6.8.11	TP defect	1.TP crack 2.TP stain(fogy& unremovable) 3.TP glue overflow to VA	Rejected	V

Remark :

Anything which is not clearly defined in 6.5~6.8 should refer to IPC-A-610E.Consumer Electronics, Non-consumer Electronics refer to Igrade and Industrial, Automobile refer to Igrade.

12.7 Others

Items not specified in this document or released on compromise should be inspected with reference to mutual agreement and limit samples.

13. HANDLING PRECAUTIONS

13.1 Mounting method

The LCD module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board. Extreme care should be needed when handling the LCD modules.

13.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[recommended below] and wipe lightly :

- •.lsopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent :

•.Water

Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated :

- Soldering flux
- •.Chlorine (Cl), Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

13.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you :

Connect any unused input terminal to Vdd or Vss, do not input any signals before power is turned on, and ground your body, work/assembly areas, assembly equipment to protect against static electricity.

13.4 Packing

Module employ LCD elements and must be treated as such.

• Avoid intense shock and falls from a height.

•. To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity.

13.5 Caution for operation

•. It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.

•. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.

•.Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.

•. If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.

•.A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

•.Usage under the maximum operating temperature, 50%Rh or less is required.

•. When fixed patterns are displayed for a long time, remnant image is likely to occur.

13.6 Storage

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

•.Storing in an ambient temperature 10°C to 30°C, and in a relative humidity of 45% to 75%. Don't expose to sunlight or fluorescent light.

•. Storing in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it . And with no desiccant.

•.Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.

•.Storing with no touch on polarizer surface by the anything else.

It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

13.7 Safety

•. It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.

•.When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

14. PRECAUTION FOR USE

14.1 A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

14.2 On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

•.When a question is arisen in this specification.

•.When a new problem is arisen which is not specified in this specifications.

•.When an inspection specifications change or operating condition change in customer is reported to ODNA, and some problem is arisen in this specification due to the change.

•.When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

15. PACKING SPECIFICATION

Please consult our technical department for detail information.